

## Ultrasoft Recovery Bridge

### Features

Ultrasoft recovery

low  $I_{RRM}$

low VF

$V_{RRM}$

Special frame design for heat dissipation

### Benefits

Reduced EMI

Reduced snubbing

Input Pin ( ~ )	
Input Pin ( ~ )	
Output ( + )	
Output ( - )	

°

		XBS30J	XBS30K	XBS30M	
			3		
Reverse Recovery Time. $I_F=0.5A, I_R=1A, I_{RR}=0.25A$	$T_{rr}$		10		us
			14		
$I^2 t$ rating for fusing ( F { • } )	$I^2 t$		98		$A^2S$
1.5			0		
( )			4		
			75		°
2			6 12		

Thermal resistance from Junction to case, lead and ambient in accordance with JESD-51.  
Unit mounted on 15mm\*12mm\*1.6mm AL pad attach 195mm\*195mm\*10mm steel plate

**RATINGS AND CHARACTERISTICS CURVES**



